

**Abstract of the Disclosure**

**[0043]** A dispensing nozzle method and apparatus is provided that may help in reducing the number of defects in integrated circuits during the manufacturing process. In one embodiment, the nozzle is configured such that at least a portion of the end of the nozzle that dispenses fluid can increase and decrease with a change in pressure, which may help to control fluid drips when the nozzle is not dispensing.